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# FCP190N65S3

## N-Channel SuperFET® III MOSFET

650 V, 17 A, 190 mΩ

### Features

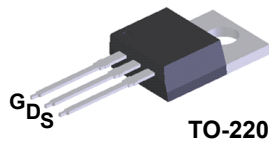
- 700 V @  $T_J = 150^\circ\text{C}$
- Typ.  $R_{DS(on)} = 159\text{ m}\Omega$
- Ultra Low Gate Charge (Typ.  $Q_g = 33\text{ nC}$ )
- Low Effective Output Capacitance (Typ.  $C_{oss(eff.)} = 300\text{ pF}$ )
- 100% Avalanche Tested
- RoHS Compliant

### Description

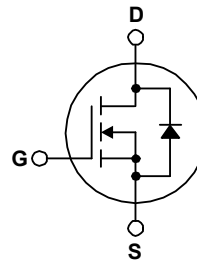
SuperFET® III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate. Consequently, SuperFET III MOSFET is very suitable for various power system for miniaturization and higher efficiency.

### Applications

- Computing / Display Power Supplies
- Telecom / Server Power Supplies
- Industrial Power Supplies



TO-220



### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	FCP190N65S3	Unit
$V_{DSS}$	Drain to Source Voltage	650	V
$V_{GSS}$	Gate to Source Voltage	- DC	$\pm 30$
		- AC (f > 1 Hz)	$\pm 30$
$I_D$	Drain Current	- Continuous ( $T_C = 25^\circ\text{C}$ )	17
		- Continuous ( $T_C = 100^\circ\text{C}$ )	11
$I_{DM}$	Drain Current	- Pulsed (Note 1)	42.5
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	76	mJ
$I_{AS}$	Avalanche Current (Note 1)	2.5	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	1.44	mJ
dv/dt	MOSFET dv/dt	100	V/ns
	Peak Diode Recovery dv/dt (Note 3)	20	
$P_D$	Power Dissipation	( $T_C = 25^\circ\text{C}$ )	144
		- Derate Above $25^\circ\text{C}$	1.15
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	FCP190N65S3	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.87	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

## Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCP190N65S3	FCP190N65S3	TO-220	Tube	N/A	N/A	50 units

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}, T_J = 25^\circ\text{C}$	650	-	-	V
		$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}, T_J = 150^\circ\text{C}$	700	-	-	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 1\text{ mA}$ , Referenced to $25^\circ\text{C}$	-	0.6	-	$\text{V}/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 650\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 520\text{ V}, T_C = 125^\circ\text{C}$	-	0.89	-	
$I_{GSS}$	Gate to Body Leakage Current	$V_{GS} = \pm 30\text{ V}, V_{DS} = 0\text{ V}$	-	-	$\pm 100$	nA

### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 1.7\text{ mA}$	2.5	-	4.5	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}, I_D = 8.5\text{ A}$	-	159	190	$\text{m}\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 20\text{ V}, I_D = 8.5\text{ A}$	-	10	-	S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V},$ $f = 1\text{ MHz}$	-	1350	-	pF
$C_{oss}$	Output Capacitance		-	30	-	pF
$C_{oss(eff.)}$	Effective Output Capacitance	$V_{DS} = 0\text{ V to } 400\text{ V}, V_{GS} = 0\text{ V}$	-	300	-	pF
$C_{oss(er.)}$	Energy Related Output Capacitance	$V_{DS} = 0\text{ V to } 400\text{ V}, V_{GS} = 0\text{ V}$	-	43	-	pF
$Q_{g(tot)}$	Total Gate Charge at 10V	$V_{DS} = 400\text{ V}, I_D = 8.5\text{ A},$ $V_{GS} = 10\text{ V}$	-	33	-	nC
$Q_{gs}$	Gate to Source Gate Charge		-	7.9	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		(Note 4)	-	14	-
ESR	Equivalent Series Resistance	$f = 1\text{ MHz}$	-	7	-	$\Omega$

### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 400\text{ V}, I_D = 8.5\text{ A},$ $V_{GS} = 10\text{ V}, R_G = 4.7\text{ }\Omega$	-	20	-	ns
$t_r$	Turn-On Rise Time		-	22	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	57	-	ns
$t_f$	Turn-Off Fall Time		(Note 4)	-	16	-

### Source-Drain Diode Characteristics

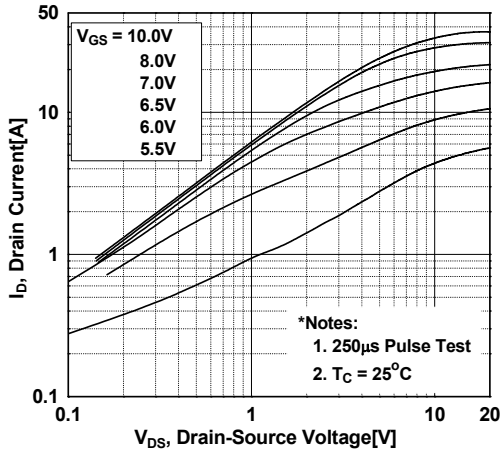
$I_S$	Maximum Continuous Source to Drain Diode Forward Current	-	-	17	A	
$I_{SM}$	Maximum Pulsed Source to Drain Diode Forward Current	-	-	42.5	A	
$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_{SD} = 8.5\text{ A}$	-	-	1.2	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_{SD} = 8.5\text{ A},$ $di_F/dt = 100\text{ A}/\mu\text{s}$	-	313	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	4.9	-	$\mu\text{C}$

#### Notes:

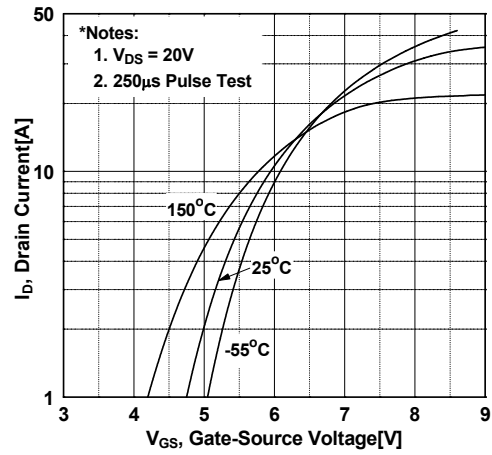
1. Repetitive rating: pulse-width limited by maximum junction temperature.
2.  $I_{AS} = 2.5\text{ A}, R_G = 25\text{ }\Omega$ , starting  $T_J = 25^\circ\text{C}$ .
3.  $I_{SD} \leq 8.5\text{ A}, di/dt \leq 200\text{ A}/\mu\text{s}, V_{DD} \leq 400\text{ V}$ , starting  $T_J = 25^\circ\text{C}$ .
4. Essentially independent of operating temperature typical characteristics.

## Typical Performance Characteristics

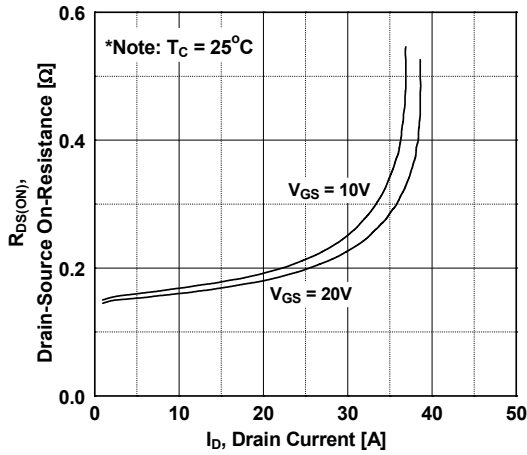
**Figure 1. On-Region Characteristics**



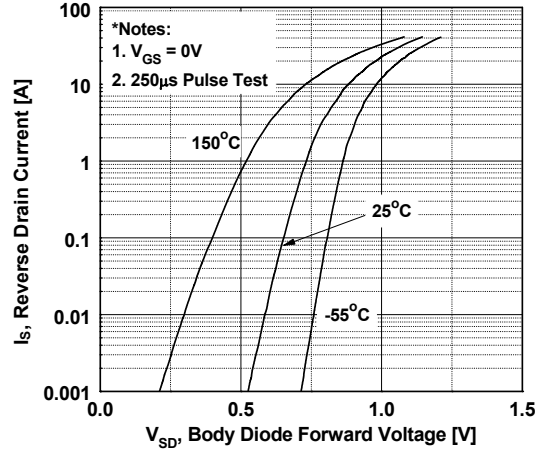
**Figure 2. Transfer Characteristics**



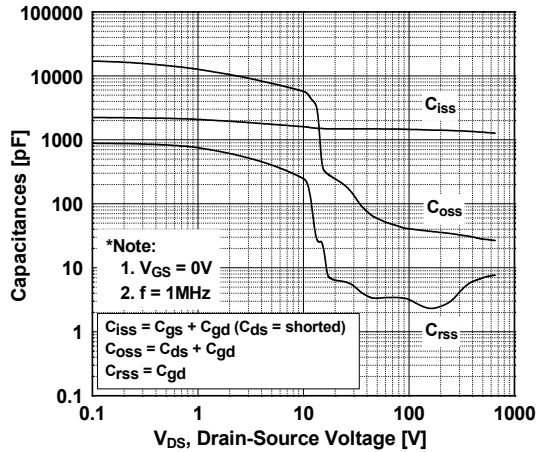
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



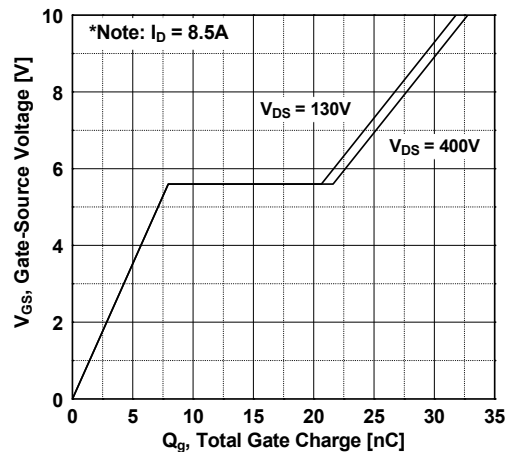
**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**



**Figure 5. Capacitance Characteristics**

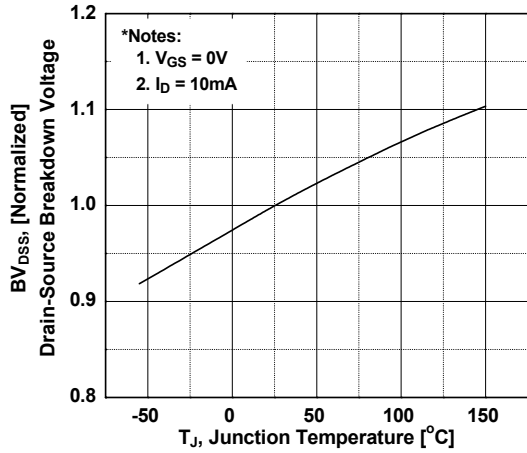


**Figure 6. Gate Charge Characteristics**

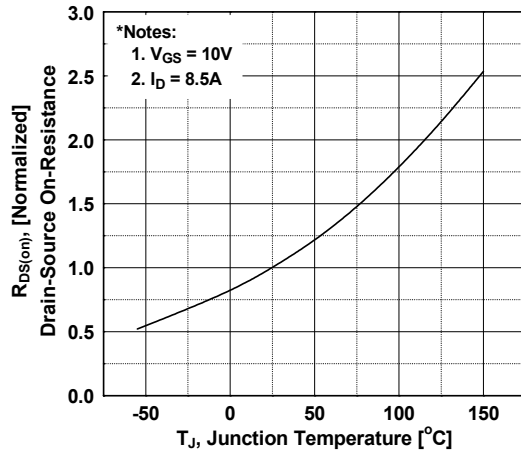


**Typical Performance Characteristics** (Continued)

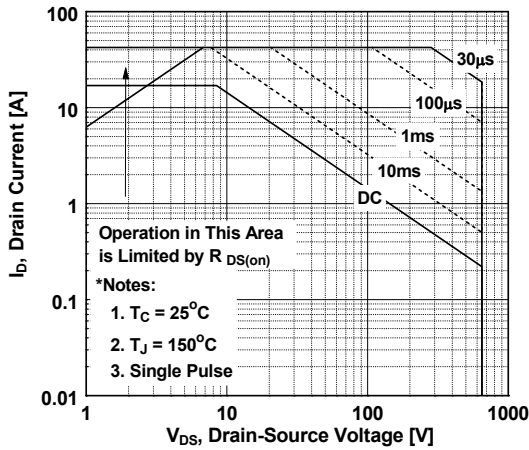
**Figure 7. Breakdown Voltage Variation vs. Temperature**



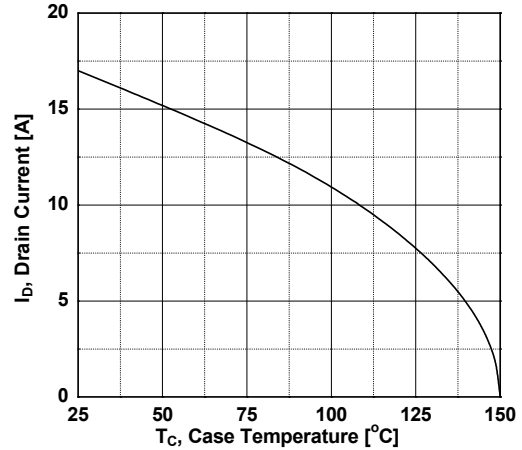
**Figure 8. On-Resistance Variation vs. Temperature**



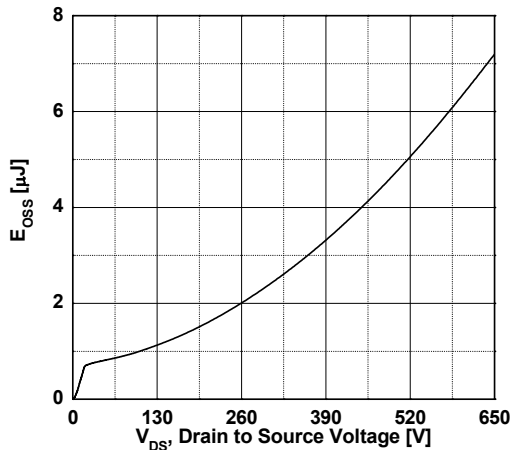
**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current vs. Case Temperature**

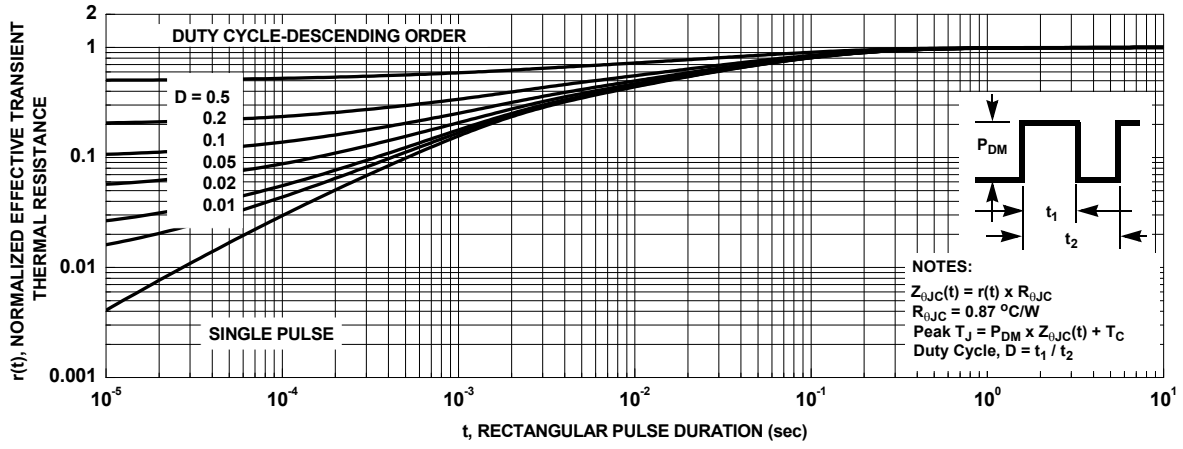


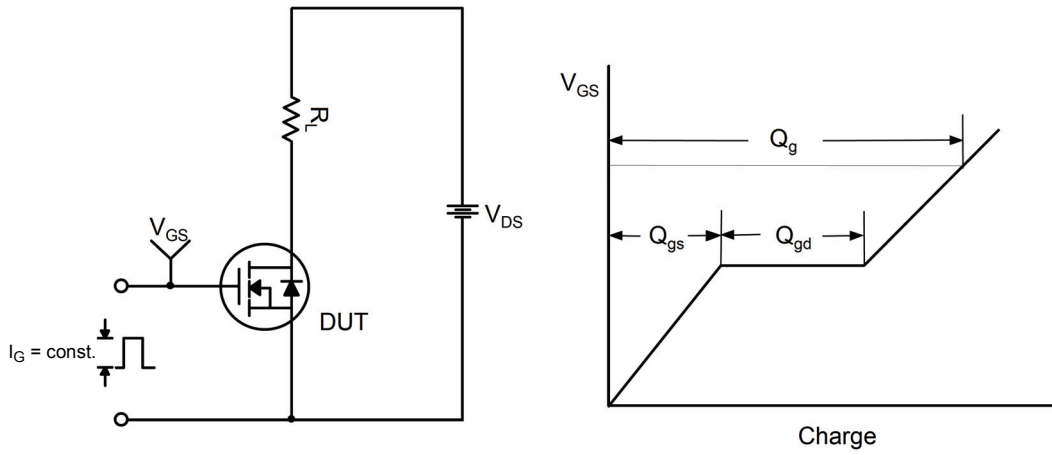
**Figure 11. Eoss vs. Drain to Source Voltage**



Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve

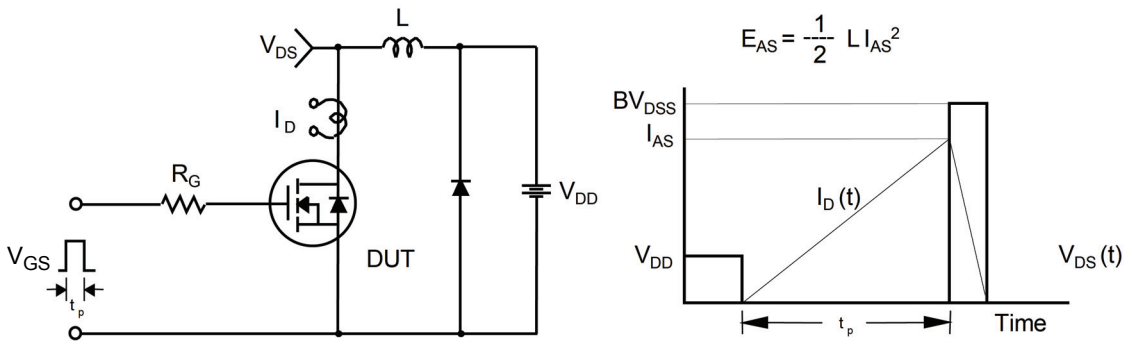




**Figure 13. Gate Charge Test Circuit & Waveform**



**Figure 14. Resistive Switching Test Circuit & Waveforms**



**Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms**



Figure 16. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms





- NOTES:
- A) REFERENCE JEDEC, TO-220, VARIATION AB
  - B) ALL DIMENSIONS ARE IN MILLIMETERS.
  - C) DIMENSIONS COMMON TO ALL PACKAGE SUPPLIERS EXCEPT WHERE NOTED [ ].
  - D) LOCATION OF MOLDED FEATURE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE)
  - E) DOES NOT COMPLY JEDEC STANDARD VALUE.
  - F) "A1" DIMENSIONS AS BELOW:  
 SINGLE GAUGE = 0.51 - 0.61  
 DUAL GAUGE = 1.10 - 1.45
  - G) DRAWING FILE NAME: TO220B03REV9
  - H) PRESENCE IS SUPPLIER DEPENDENT
  - I) SUPPLIER DEPENDENT MOLD LOCKING HOLES IN HEATSINK.

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